

C1206X103M1GEC

ESD SMD Comm COG, Ceramic, 0.01 uF, 20%, 100 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 1206, 1.5 mm



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General Information	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	20 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
т	0.9mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

Bulk, Bag

1

Packaging Specifications

Packaging Packaging Quantity Specifications Capacitance 0.01 uF **Measurement Condition** 1 kHz 1.0Vrms Tolerance 20% 100 VDC Voltage DC ESD Level per AEC-Q200 25,000 V ESD Level Dielectric Withstanding Voltage 250 VDC **Temperature Range** -55/+125°C Temp. Coefficient COG Capacitance Change with Reference to +25°C and 0 VDC 30 ppm/C, 1kHz 1.0Vrms Applied (TCC) **Dissipation Factor** 0.1%1 kHz 1.0Vrms Aging Rate 0% Loss/Decade Hour Insulation Resistance 100 GOhms

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